

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6979622

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SRINIVAS V. PIETAMBARAM	04/05/2019
TAREK IBRAHIM	04/09/2019
KRISTOF DARMAWIKARTA	04/15/2019
RAHUL N. MANEPALLI	04/05/2019
DEBENDRA MALLIK	04/08/2019
ROBERT L. SANKMAN	04/08/2019
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BOULEVARD
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17492476
CORRESPONDENCE DATA	
Fax Number:	(503)796-2900
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(503) 222-9981
Email:	svillarreal@schwabe.com
Correspondent Name:	JUSTIN K. BRASK
Address Line 1:	1211 SW 5TH AVENUE, STE. 1600
Address Line 4:	PORTLAND, OREGON 97204
ATTORNEY DOCKET NUMBER:	AB6062-US-C1 111079267144
NAME OF SUBMITTER:	JUSTIN K. BRASK
SIGNATURE:	/Justin K. Brask/
DATE SIGNED:	10/20/2021
Total Attachments: 2	

source=AB6062-US ASSIGN Executed#page1.tif

source=AB6062-US ASSIGN Executed#page2.tif

PATENT

REEL: 057877 FRAME: 0988

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Srinivas V. Pietambaram, Tarek Ibrahim, Kristof Darmawikarta, Rahul N. Manepalli,
Debendra Mallik, Robert L. Sankman>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

INORGANIC-BASED EMBEDDED-DIE LAYERS FOR MODULAR SEMICONDUCTIVE DEVICES

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on March 25, 2019 as

United States of America Application Number 16/363,698

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute

73-20000-1, 2000-01-01
(20-00000-1) 1000, 2000-01-01
12000-1-000

Intel Docket No.: AB6062-US
SLW Reference No.: (AB6062-US)
1884.648US1

all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

P. V. R. Srinivas

Srinivas V. Pietambaram

04/05/2019

Date Signed

Tarek Ibrahim

Tarek Ibrahim

4/9/2019

Date Signed

Kristof Darmawikarta

Kristof Darmawikarta

4/15/19

Date Signed

Rahul N. Manepalli

Rahul N. Manepalli

04/15/19

Date Signed

Debendra Mallik

Debendra Mallik

4/8/19

Date Signed

Robert L. Sankman

Robert L. Sankman

4/8/19

Date Signed